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<ul> <li>Three Bidirectional Transceivers</li> <li>Driver Meets or Exceeds ANSI Standard</li> </ul>	DW PACKAGE (TOP VIEW)
EIA/TIA-422-B and RS-485 and ITU Recommendation V.11	1D 1 20 1B 1DIR 2 19 1A
Two Skew Limits Available	NC 3 18 NC
<ul> <li>Designed to Operate Up to 20 Million Data Transfers per Second (FAST-20 SCSI)</li> </ul>	GND [] 4 17 ]] NC NC [] 5 16 ]] V <sub>CC</sub>
<ul> <li>High-Speed Advanced Low-Power Schottky Circuitry</li> </ul>	2D [] 6 15 [] 2B 2DIR [] 7 14 ]] 2A
<ul> <li>Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments</li> </ul>	NC [] 8 13 ]] 3B 3D [] 9 12 ]] 3A
<ul> <li>Wide Positive and Negative Input/Output Bus Voltage Ranges</li> </ul>	3DIR 10 11 NC
<ul> <li>Driver Output Capacity ±60 mA</li> </ul>	
Thermal Shutdown Protection	J PACKAGE (TOP VIEW)
<ul> <li>Driver Positive- and Negative-Current Limiting</li> </ul>	
<ul> <li>Receiver Input Impedances 12 kΩ Min</li> </ul>	1DIR 2 13 1A
Receiver Input Sensitivity ±300 mV Max	GND 3 12 V <sub>CC</sub>
Receiver Input Hysteresis 60 mV Typ	2D 4 11 2B
Operate From a Single 5-V Supply	2DIR 5 10 2A 3D 6 9 3B
<ul> <li>Glitch-Free Power-Up and Power-Down Protection</li> </ul>	3DIR [ 7 8] 3A

description

Each Channel

**Feature Independent Direction Controls for** 

The SN75ALS170 and SN75ALS170A triple differential bus transceivers are monolithic integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. It is designed for balanced transmission lines and the driver meets ANSI Standards EIA/TIA-422-B and RS-485 and both the driver and receiver meet ITU Recommendation V.11. The SN75ALS170A is designed for FAST-20 SCSI and can transmit or receive data pulses as short as 30 ns with a maximum skew of 5 ns.

The SN75ALS170 and SN75ALS170A operate from a single 5-V power supply. The drivers and receivers have active-high and active-low enables, respectively, which are internally connected together to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or  $V_{CC} = 0$ . These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The SN75ALS170 and the SN75ALS170A are characterized for operation from 0°C to 70°C.

AVAILABLE OF HONS							
SKEW LIMIT	T PART NUMBER						
10 ns	SN75ALS170DW	SN75ALS170J					
5 ns	SN75ALS170ADW						

AVAILARI E OPTIONS



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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#### **Function Tables**

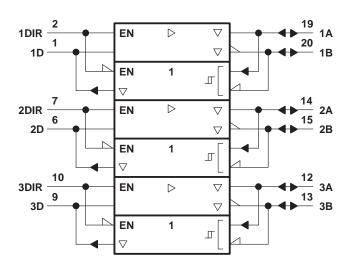
EACH DRIVER							
INPUT	DIR	OUTI	PUTS				
D	DIK	Α	В				
Н	Н	Н	L				
L	Н	L	Н				
Х	L	Z	Z				

#### EACH RECEIVER

DIFFERENTIAL INPUTS A – B	DIR	OUTPUT R
$V_{ID} \ge 0.3 V$	L	Н
$-0.3 \text{ V} < \text{V}_{\text{ID}} < 0.3 \text{ V}$	L	?
$V_{ID} \le -0.3 V$	L	L
Х	н	Z
Open	L	н

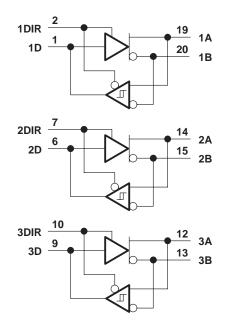
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

### logic symbol<sup>†</sup>



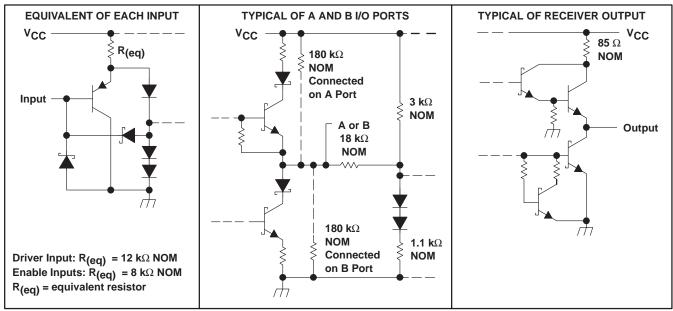
<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW package.

### logic diagram (positive logic)





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#### schematics of inputs and outputs

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1)	
Voltage range at any bus terminal	$\dots \dots -7$ V to 12 V
Enable input voltage, V <sub>1</sub>	
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW package	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package .	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE									
PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING						
DW	1125 mW	9.0 mW/°C	720 mW						
J	1025 mW	8.2 mW/°C	656 mW						



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#### recommended operating conditions

		MIN	TYP	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.75	5	5.25	V
Voltage at any bue terminal (concretely or				12	V
voltage at any bus terminal (separately of				-7	v
High-level input voltage, VIH	D, DIR	2			V
Low-level input voltage, VIL	D, DIR			0.8	V
Differential input voltage, $V_{ID}$ (see Note 2)		±12		V	
	Driver			-60	mA
High-level output current, IOH	tv voltage, V <sub>IL</sub> D, DIR but voltage, V <sub>ID</sub> (see Note 2) tput current, I <sub>OH</sub> Driver Receiver put current, I <sub>OL</sub> Driver Receiver			-400	μA
	Driver			60	A
ow-level output current, IOL	Receiver			8	mA
Operating free-air temperature, TA	·	0		70	°C

NOTE 2: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



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#### **DRIVER SECTION**

#### electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS <sup>†</sup>	MIN <sup>-</sup>	түр‡	MAX	UNIT
VIK	Input clamp voltage	lı = – 19 mA				-1.5	V
VO	Output voltage	IO = 0		0		6	V
VOH	High-level output voltage	V <sub>CC</sub> = 4.75 V, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -55 mA	2.7			V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = 4.75 V, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 55 mA			1.7	V
VOD1	Differential output voltage	IO = 0		1.5		6	V
V <sub>OD2</sub>	Differential output voltage	R <sub>L</sub> = 100 Ω,	See Figure 1	1/2 VOD1 or 2§			V
		R <sub>L</sub> = 54 Ω,	See Figure 1	1.5	2.5	5	V
V <sub>OD3</sub>	Differential output voltage	$V_{\text{test}} = -7 \text{ V to } 12 \text{ V},$	See Figure 2	1.5		5	V
$\Delta \mid V_{OD} \mid$	Change in magnitude of differential output voltage¶					±0.2	V
VOC	Common-mode output voltage	$R_L$ = 540 Ω or 100 Ω,	See Figure 1			3	V
Δ   V <sub>OC</sub>	Change in magnitude of common-mode output voltage¶	-				±0.2	V
	Ordersteiner	Output disabled,	V <sub>O</sub> = 12 V			1	
0	Output current	See Note 3	V <sub>O</sub> = -7 V	1		-0.8	mA
ιн	High-level input current	V <sub>I</sub> = 2.4 V	•			20	μA
	Low-level input current	V <sub>I</sub> = 0.4 V		1		-400	μA
		$V_{O} = -6 V$				-250	
		$V_{O} = 0$				-150	
IOS	Short-circuit output current	$V_{O} = V_{CC}$				250	mA
		V <sub>O</sub> = 8 V				250	
	Quanta summat	Neteral	Outputs enabled		69	90	
△   Voc   <sup>I</sup> O <sup>I</sup> IH <sup>I</sup> IL <sup>I</sup> OS <sup>I</sup> CC	Supply current	No load	Outputs disabled		57	78	mA

<sup>†</sup> The power-off measurement in ANSI Standard EIA/TIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs. <sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^{\circ}\text{C}$ . § The minimum  $V_{OD2}$  with a 100- $\Omega$  load is either 1/2  $V_{OD1}$  or 2 V, whichever is greater.

¶ Δ | V<sub>OD</sub> | and Δ | V<sub>OC</sub> | are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub> respectively, that occur when the input is changed from a high level to a low level.

NOTE 3: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions. The EIA/TIA-422-B limit does not apply for a combined driver and receiver terminal.



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#### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST COND	ITIONS	MIN	TYP†	MAX	UNIT
		ALS170	RL = 54 Ω,	С <sub>L</sub> = 50 рF,	3	8	13	
		ALS170A	T <sub>A</sub> =25°C,	See Figure 3	5.5	8	10.5	
<sup>t</sup> d(OD)	Differential output delay time	ALS170	$R_{L1} = R_{L3} = 165 \Omega,$ $C_L = 60 \text{ pF},$	R <sub>L2</sub> = 75 Ω, T <sub>A</sub> =25°C,	3	8	13	ns
		ALS170A	See Figure 4	1 <sub>A</sub> =23 0,	5.5	8	10.5	
			$R_L = 54 \Omega$ , See Figure 3	C <sub>L</sub> = 50 pF,		1	5	ns
<sup>t</sup> sk(p)	Pulse skew <sup>‡</sup>		$R_{L1} = R_{L3} = 165 \Omega,$ $C_L = 60 \text{ pF},$	R <sub>L2</sub> = 75 Ω, See Figure 4		1	5	ns
		ALS170	R <sub>L</sub> = 54 Ω,	C <sub>L</sub> = 50 pF,			10	
• • • • •	Skew limit§	ALS170A	See Figure 3				5	
<sup>t</sup> sk(lim)	Skew mmts	ALS170	$R_{L1} = R_{L3} = 165 \Omega$ ,	R <sub>L2</sub> = 75 Ω,			10	ns
		ALS170A	$C_{L} = 60 \text{ pF},$	See Figure 4			5	
	Differential output transition time		$R_L = 54 \Omega$ , See Figure 3	C <sub>L</sub> = 50 pF,	3	8	13	20
<sup>t</sup> t(OD)	Differential-output transition time		$R_{L1} = R_{L3} = 165 \Omega$ , $C_L = 60 \text{ pF}$ ,	R <sub>L2</sub> = 75 Ω, See Figure 4	3	8	13	ns

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^{\circ}C$ .

 Pulse skew is defined as the |t<sub>d</sub>(ODH)-t<sub>d</sub>(ODL)| of each channel.
 Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one  $V_{CC}$  and operating temperature within the recommended operating conditions.

SYMBOL EQUIVALENTS							
DATA SHEET PARAMETER	EIA/TIA-422-B	RS-485					
VO	V <sub>oa</sub> , V <sub>ob</sub>	V <sub>oa</sub> , V <sub>ob</sub>					
VOD1	VO	VO					
VOD2	V <sub>t</sub> (R <sub>L</sub> = 100 Ω)	$V_t (R_L = 54 \Omega)$					
V <sub>OD3</sub>		V <sub>t</sub> (Test Termination Measurement 2)					
V <sub>test</sub>		V <sub>tst</sub>					
$\Delta   V_{OD}  $	$   V_t   -   \overline{V}_t   $	$   V_t   -   \overline{V}_t   $					
V <sub>OC</sub>	V <sub>OS</sub>	V <sub>OS</sub>					
∆   V <sub>OC</sub>	V <sub>os</sub> – V <sub>os</sub>	V <sub>os</sub> – V <sub>os</sub>					
los	I <sub>sa</sub>  ,   I <sub>sb</sub>						
IO	I <sub>xa</sub>  ,   I <sub>xb</sub>	l <sub>ia</sub> , l <sub>ib</sub>					

#### SYMBOL FOUIVALENTS



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#### **RECEIVER SECTION**

# electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST (	CONDITIONS	MIN	TYP†	MAX	UNIT
VIT+	Positive-going input threshold voltage	V <sub>O</sub> = 2.7 V,	$I_{O} = -0.4 \text{ mA}$			0.3	V
VIT-	Negative-going input threshold voltage	V <sub>O</sub> = 0.5 V,	I <sub>O</sub> = 8 mA	-0.3‡			V
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT +</sub> – V <sub>IT –</sub> )				60		mV
VIK	Enable-input clamp voltage	lı = – 18 mA				-1.5	V
Vон	High-level output voltage	V <sub>ID</sub> = 300 mV, See Figure 5	I <sub>OH</sub> = -400 μA,	2.7			V
VOL	Low-level output voltage	$V_{ID} = -300 \text{ mV},$ See Figure 5	I <sub>OL</sub> = 8 mA,			0.45	V
	High impedance state output ourrent	V <sub>O</sub> = 2.4 V				20	
loz	High-impedance-state output current	V <sub>O</sub> = 0.4 V				-400	μA
		Other input = 0,	V <sub>I</sub> = 12 V			1	mA
I	Line input current	See Note 4	$V_{I} = -7 V$			-0.8	ША
IH	High-level enable-input current	VIH = 2.7 V				20	μΑ
IL	Low-level enable-input current	V <sub>IL</sub> = 0.4 V				-100	μΑ
ſ	Input resistance			12			kΩ
los	Short-circuit output current	V <sub>ID</sub> = 300 mV,	$V_{O} = 0$	-15		-85	mA
	Supply autropt	No. I and	Outputs enabled	69	69	90	
lcc	Supply current	No load	Outputs disabled		57	78	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^{\circ}C$ .

<sup>‡</sup> The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 4: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature range

	PARAMETER		TEST CONDITIONS	MIN	түр†	MAX	UNIT
t=	Propagation delay time, low-to-high-level	ALS170		9		19	ns
<sup>t</sup> PLH	output	ALS170A	$V_{ID} = -1.5 V$ to 1.5 V, $C_{I} = 15 pF$ , $T_{A} = 25^{\circ}C$ ,	11.5		16.5	115
	Propagation delay time, high-to-low-level	ALS170	See Figure 6 $A = 25 C$ ,	9		19	20
<sup>t</sup> PHL	output	ALS170A	J	11.5		16.5	ns
4	Pulse skew§	ALS170			2	6	
<sup>t</sup> sk(p)		ALS170A	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$			5	ns
<b>1</b>	Skew limit¶	ALS170	$C_L = 15  \text{pF},$ See Figure 6			10	20
<sup>t</sup> sk(lim)		ALS170A	1			5	ns

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

§ Pulse skew is defined as the |tpLH-tpHL| of each channel.

Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one V<sub>CC</sub> and operating temperature within the recommended operating conditions.



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#### PARAMETER MEASUREMENT INFORMATION

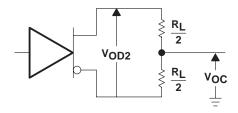


Figure 1. Driver V<sub>OD</sub> and V<sub>OC</sub>

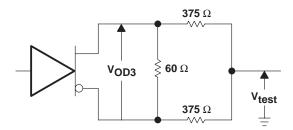
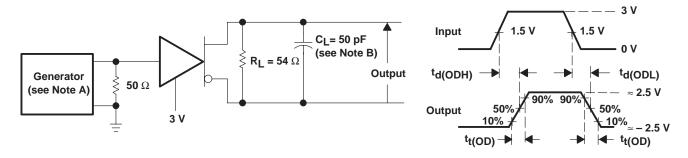


Figure 2. Driver V<sub>OD3</sub>



**TEST CIRCUIT** 

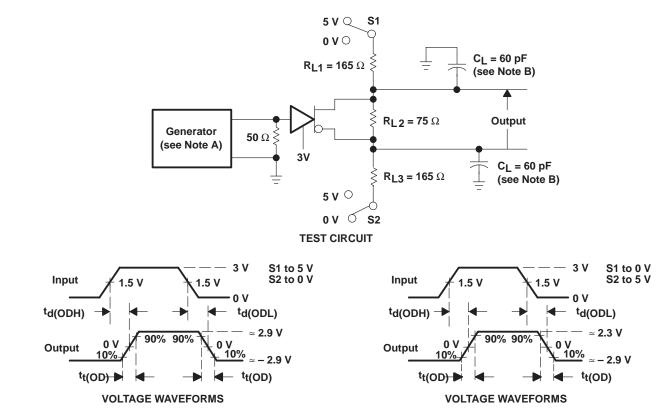
**VOLTAGE WAVEFORMS** 

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>f</sub>  $\leq$  6 ns, t<sub>f</sub>  $\leq$  6 ns, Z<sub>O</sub> = 50  $\Omega$ .
  - B.  $C_{L}$  includes probe and jig capacitance.

#### Figure 3. Driver Test Circuit and Voltage Waveforms

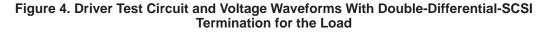


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#### PARAMETER MEASUREMENT INFORMATION

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>f</sub>  $\leq$  6 ns, t<sub>f</sub>  $\leq$  6 ns, Z<sub>Q</sub> = 50  $\Omega$ .
  - B. CL includes probe and jig capacitance.



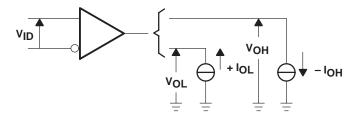
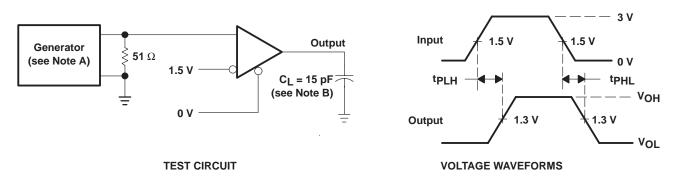


Figure 5. Receiver VOH and VOL



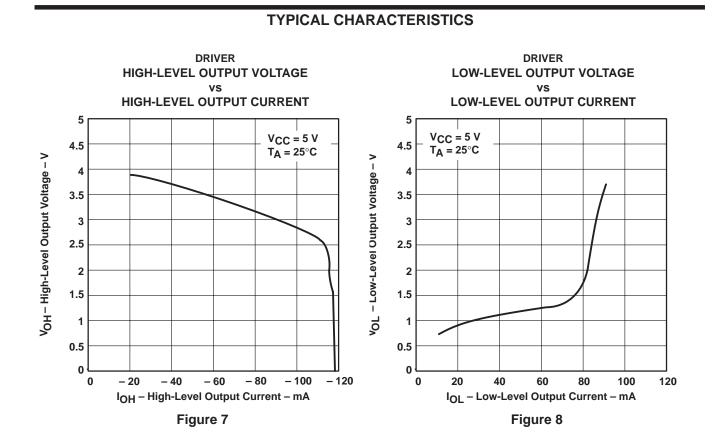
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#### PARAMETER MEASUREMENT INFORMATION



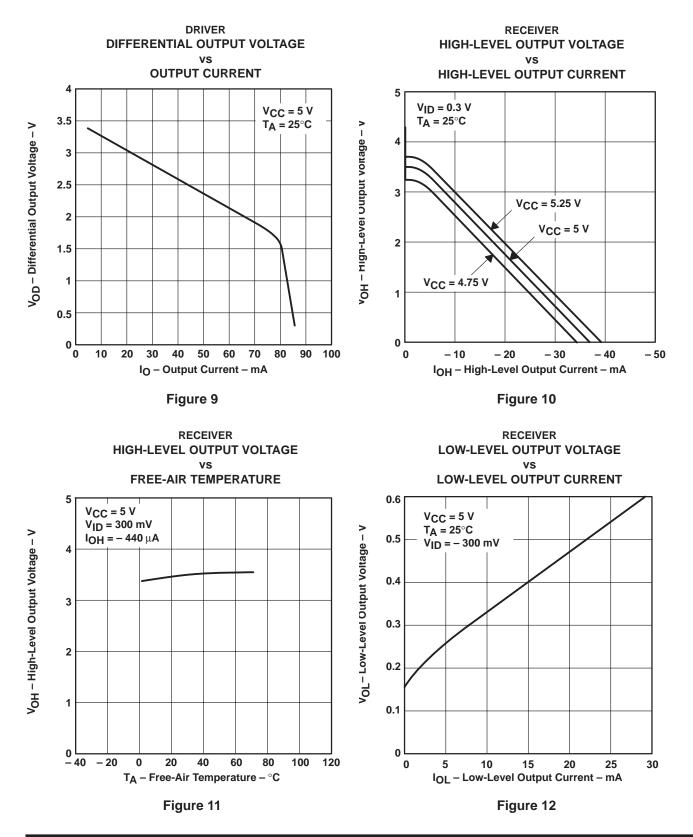
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>f</sub>  $\leq$  6 ns, t<sub>f</sub>  $\leq$  6 ns, Z<sub>O</sub> = 50  $\Omega$ .
  - B. CL includes probe and jig capacitance.

#### Figure 6. Receiver Test Circuit and Voltage Waveforms





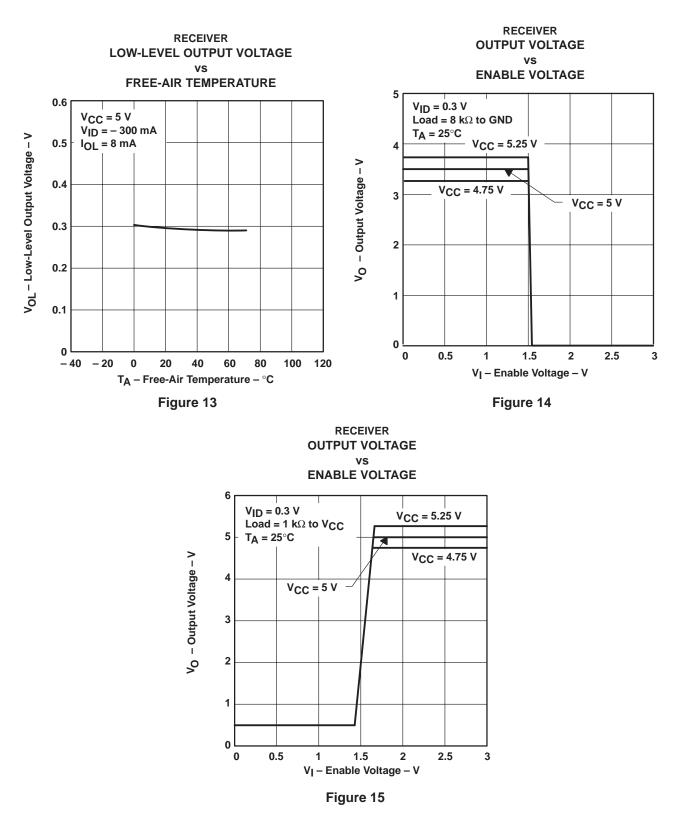
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#### **TYPICAL CHARACTERISTICS**



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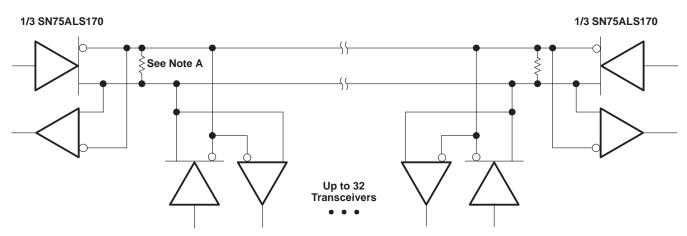


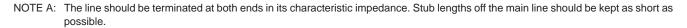




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**APPLICATION INFORMATION** 







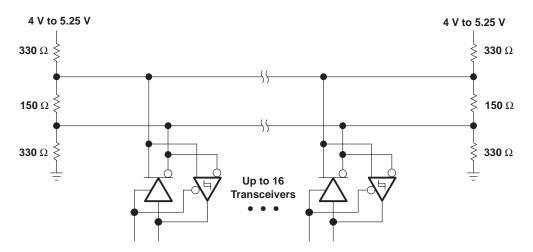
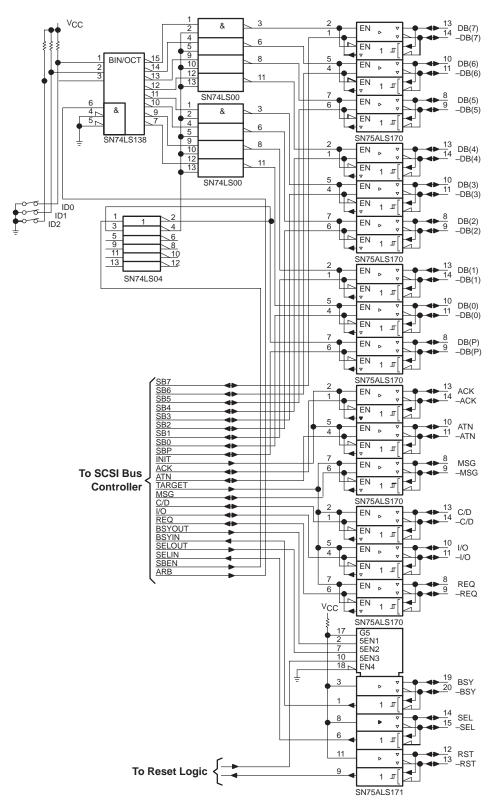


Figure 17. Typical Differential SCSI Application Circuit



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#### **APPLICATION INFORMATION**





TEXAS

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75ALS170ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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10-May-2007

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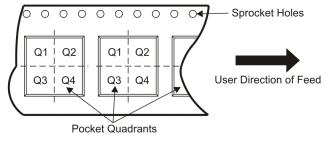
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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*	All dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN75ALS170ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.1	2.65	12.0	24.0	Q1
	SN75ALS170DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.1	2.65	12.0	24.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS170ADWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN75ALS170DWR	SOIC	DW	20	2000	346.0	346.0	41.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



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